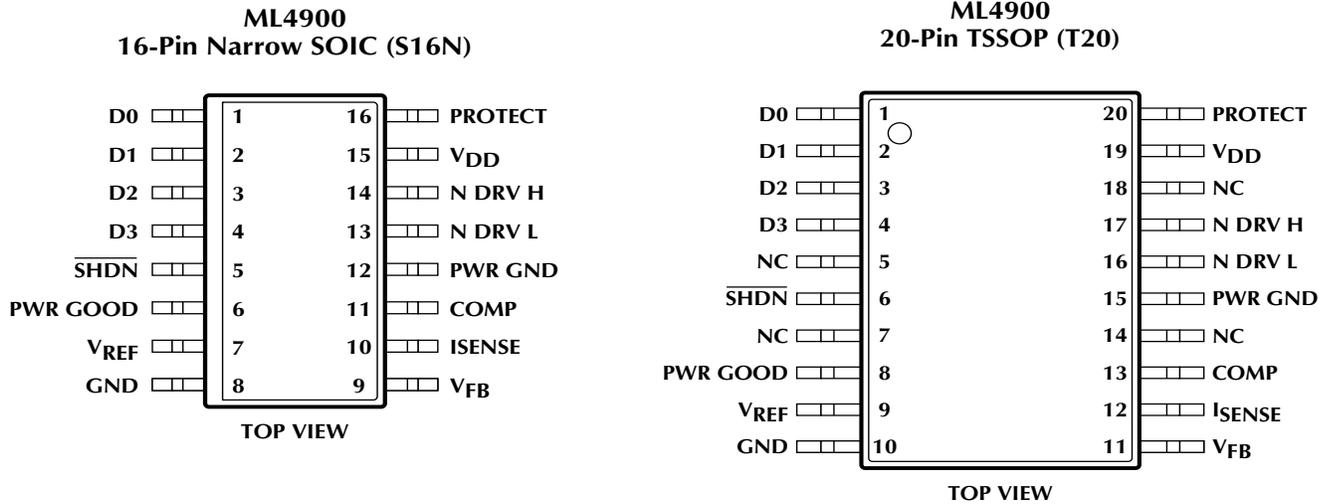




# ML4900

## PIN CONFIGURATION



## PIN DESCRIPTION (Pin Number in Parentheses is for TSSOP Version)

PIN	NAME	FUNCTION	PIN	NAME	FUNCTION
1 (1)	D0	LSB input to the DAC which sets the output voltage	8 (10)	GND	Analog signal ground
2 (2)	D1	Input to the DAC which sets the output voltage	9 (11)	V <sub>FB</sub>	Output voltage feedback pin
3 (3)	D2	Input to the DAC which sets the output voltage	10 (12)	I <sub>SENSE</sub>	Current sense input
4 (4)	D3	MSB input to the DAC which sets the output voltage	11 (13)	COMP	Connection for the compensation and optional soft-start delay network
5 (6)	SHDN	Grounding this pin shuts down the regulator	12 (15)	PWR GND	Power ground
6 (8)	PWR GOOD	This open collector output goes low whenever SHDN goes low or when the output is not within ±10% of its nominal value	13 (16)	N DRV L	Synchronous rectifier driver output
7 (9)	V <sub>REF</sub>	Bypass connection for the internal 3.5V reference	14 (17)	N DRV H	Buck switch driver output
			15 (19)	V <sub>DD</sub>	12V power supply input
			16 (20)	PROTECT	Connection for the integrating current limit network and the UVLO monitor for the 5V supply

## ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

$V_{DD}$ .....	13.5V
Peak Driver Output Current .....	$\pm 2A$
$V_{FB}$ Voltage .....	GND - 0.3V to 5.5V
$I_{SENSE}$ Voltage .....	GND - 0.5V to 5.5V
All Other Analog Inputs .....	GND - 0.3V to $V_{DD} + 0.3V$
$\overline{SHDN}$ Input Current .....	100 $\mu A$
Junction Temperature .....	150°C
Storage Temperature Range .....	-65°C to 150°C

Lead Temperature (Soldering, 10 sec) .....	260°C
Thermal Resistance ( $\theta_{JA}$ )	
16-Pin Narrow SOIC .....	100°C/W
20-Pin TSSOP .....	143°C/W

## OPERATING CONDITIONS

Temperature Range .....	0°C to 70°C
$V_{DD}$ Range .....	11.4V to 12.6V
PROTECT (5V Supply) Range .....	4.75V to 5.25V

## ELECTRICAL CHARACTERISTICS

Unless otherwise specified,  $V_{DD} = 12V$ , PROTECT =  $\overline{SHDN} = 5V$ ,  $T_A$  = Operating Temperature Range (Note 1)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>REFERENCE</b>						
$V_{REF}$	Output Voltage		3.51	3.535	3.56	V
	Line Regulation	$11V < V_{DD} < 13V$		0.5		mV/V
<b>UV LOCKOUT</b>						
	$V_{DD}$ Start-up Threshold		10.2	10.5	10.8	V
	$V_{DD}$ Hysteresis		300	450	600	mV
	PROTECT (5V) Start-up Threshold		4.25	4.4	4.5	V
	PROTECT (5V) Hysteresis		400	450	500	mV
<b>SHUTDOWN</b>						
	Input Low Voltage				0.8	V
	Input High Voltage		2.0			V
	Delay to Output			50		ns
<b>POWER GOOD COMPARATOR</b>						
	Output Voltage in Regulation	5k $\Omega$ pull-up to 5V	4.8			V
	Output Voltage out of Regulation	$V_{FB} < 90\% V_{DAC}$ or $> 110\% V_{DAC}$			0.4	V
	Output Voltage in Shutdown	$\overline{SHDN} = 0V$ , 5k $\Omega$ pull-up to 5V			0.4	V
<b>BUCK REGULATOR</b>						
	Oscillator Frequency		160	200	230	kHz
	Duty Cycle Ratio	DAC (D3-D0) Code = 0100, $V_{FB} = 0V$	85		95	%
		DAC (D3-D0) Code = 0100, $V_{FB} > 3.193V$			0	%
	DAC (D3-D0) Input Low Voltage				0.8	V
	DAC (D3-D0) Input High Voltage		2.0			V

## ELECTRICAL CHARACTERISTICS (Continued)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>BUCK REGULATOR (continued)</b>						
	V <sub>FB</sub> Threshold Voltage	DAC (D3-D0) Code = 0000	3.495	3.535	3.575	V
		DAC (D3-D0) Code = 0001	3.400	3.434	3.468	V
		DAC (D3-D0) Code = 0010	3.300	3.333	3.366	V
		DAC (D3-D0) Code = 0011	3.200	3.232	3.264	V
		DAC (D3-D0) Code = 0100	3.100	3.131	3.162	V
		DAC (D3-D0) Code = 0101	3.000	3.03	3.060	V
		DAC (D3-D0) Code = 0110	2.900	2.929	2.958	V
		DAC (D3-D0) Code = 0111	2.800	2.828	2.856	V
		DAC (D3-D0) Code = 1000	2.700	2.727	2.754	V
		DAC (D3-D0) Code = 1001	2.600	2.626	2.652	V
		DAC (D3-D0) Code = 1010	2.500	2.525	2.550	V
		DAC (D3-D0) Code = 1011	2.400	2.424	2.448	V
		DAC (D3-D0) Code = 1100	2.299	2.323	2.347	V
		DAC (D3-D0) Code = 1101	2.198	2.222	2.246	V
		DAC (D3-D0) Code = 1110	2.097	2.121	2.145	V
DAC (D3-D0) Code = 1111			0.8	V		
	I <sub>SENSE</sub> Threshold Voltage		-66	-73	-80	mV
	I <sub>SENSE</sub> Hysteresis			3		mV
	PROTECT Discharge Current	V(I <sub>SENSE</sub> ) = -100mV		35		mA
	PROTECT Leakage Current			±100		nA
	Transition Time, N DRV H and N DRV L	C <sub>L</sub> = 5000pF, 10-90%		40		ns
<b>SUPPLY</b>						
	V <sub>DD</sub> Current	$\overline{\text{SHDN}} = 0\text{V}$ DAC (D3-D0) Code = 0000		300	450	μA
		$\overline{\text{SHDN}} = 5\text{V}$ , V <sub>FB</sub> = 5V		1	2	mA
		$\overline{\text{SHDN}} = 5\text{V}$ , V <sub>FB</sub> = 0V, C <sub>L</sub> = 5000pF		30		mA

**Note 1:** Limits are guaranteed by 100% testing, sampling, or correlation with worst case test conditions.

## FUNCTIONAL DESCRIPTION

The ML4900 PWM controller permits the construction of a simple yet sophisticated power supply for Intel's Pentium Pro microprocessor which meets the guidelines of Intel's Application Note AP-523. This can be built either as a Voltage Regulator Module (VRM) or as dedicated motherboard circuitry. The ML4900 controls two N-channel MOSFETs in a synchronous buck regulator circuit, to convert a 5V input to the voltage required by the microprocessor. The output voltage can be any set to any one of 15 output voltages from 2.1V to 3.5V, in steps of 100mV, as selected by an onboard DAC. Other features which facilitate the design of DC-DC converters for any type of processor include a trimmed 1% reference, special transient-response optimization in the feedback paths, a shutdown input, input and output power good monitors, and overcurrent protection.

### 4-BIT DAC

The inputs of the internal 4-bit DAC come from open collector signals provided by the Pentium Pro. These signals specify what supply voltage the microprocessor requires. The output voltage of the buck converter is compared directly with the DAC voltage to maintain regulation. D3 is the MSB input and D0 is the LSB input of the DAC. The output voltage set by the DAC is 1% above the Pentium Pro's nominal operating voltage to counteract the effects of connector and PC trace resistance, and of the instantaneous output voltage droop which occurs when a transient load is applied. The output of the DAC therefore ranges from 2.121V to 3.535V in 100mV steps. For code 1111, the N DRV H output is disabled, and the output voltage is zero.

### VOLTAGE FEEDBACK LOOP

The ML4900 contains two control loops to improve the load transient response. The output voltage is directly monitored via the  $V_{FB}$  pin and compared to the desired output voltage set by the internal 4-bit DAC. When the output voltage is within  $\pm 3\%$  of the DAC voltage, the proportional control loop (closed by the voltage error amplifier) keeps the output voltage at the correct value. If the output falls below the DAC voltage by more than 3%, one side of the transient loop is activated, forcing the output of the ML4900 to maximum duty cycle until the output comes back within the  $\pm 3\%$  limit. If the output voltage rises above the DAC voltage by more than 3%, the other side of the transient loop is activated, and the upper MOSFET drive is disabled until the output comes back within the  $\pm 3\%$  limit. During start-up, the transient loop is disabled until the output voltage is within -3% of the DAC voltage.

### POWER GOOD (PWR GOOD)

An open drain signal is provided by the ML4900 which tells the microprocessor when the entire power system is

functioning within the expected limits. PWR GOOD will be false (low) if either the 5V or 12V supply is not in regulation, when the  $\overline{\text{SHDN}}$  pin is pulled low, or when the output is not within  $\pm 10\%$  of the nominal output voltage selected by the internal DAC.

When PWR GOOD is false, the PWR GOOD voltage window is held to  $\pm 3\%$ ; when PWR GOOD is true (high), the window is expanded to  $\pm 10\%$ . Using different windows for coming into and going out of regulation makes sure that PWR GOOD does not oscillate during the start-up of the microprocessor.

### INTERNAL REFERENCE

The ML4900 contains a 3.535V, temperature compensated, precision band-gap reference. The  $V_{REF}$  pin is connected to the output of this reference, and should be bypassed with a 100nF to 220nF ceramic capacitor for proper operation.

### OVERCURRENT PROTECTION

When the output of the buck converter sees an overcurrent condition ( $I_{OUT}$  exceeds the current limit set point  $I_{SET}$ ), the ML4900 will operate in a "hiccup" mode until the overcurrent condition has been removed.

During an overcurrent condition, a current sink within the ML4900 draws a small current (35 $\mu$ A) out of the PROTECT pin for the time during which  $I_{OUT} > I_{SET}$ . If this current sink is activated over a number of cycles, the voltage on the PROTECT pin will drop below 4V, signalling a sustained overcurrent or short circuit at the load. This will cause the N DRV H output to turn off. The converter will remain in an off state until the capacitor attached to the PROTECT pin has charged back to 4.4V, at which time the converter is re-enabled and tries to resume normal operation. If the fault causing the overcurrent condition has not been cleared, the overcurrent protection cycle will repeat.

### UNDERVOLTAGE LOCKOUT

The ML4900 has undervoltage lockout protection circuits for both the 12V ( $V_{DD}$ ) and 5V (PROTECT) supplies. The hysteresis voltage is typically 400mV for each supply. During an input undervoltage condition, the internal reference and voltage monitor circuits remain in operation, but N DRV H and N DRV L are disabled and the PWR GOOD output will be false (low).

### COMPENSATION/SOFT-START

This pin connects to the output of the transconductance amplifier which forms the gain block for the ML4900's proportional control loop. An RC network from this pin to GND is used to compensate the amplifier.

## DESIGN CONSIDERATIONS

This section is a quick-check guide for getting ML4900 circuits up and running, with a special emphasis on Pentium Pro applications. All component designators refer to the circuit shown in Figure 1.

### COMPENSATION

The R and C values connected to the COMP pin for loop compensation are 330k $\Omega$  and 33pF, respectively. These values yield stable operation and rapid transient response for a most values of L and C<sub>OUT</sub> (1 $\mu$ H to 5 $\mu$ H, 1200 $\mu$ F to 10,000 $\mu$ F), and will generally not need to be altered. If changes do need to be made, note that the drive capability of the transconductance error amplifier is typically 10 $\mu$ A, its Z<sub>OUT</sub> is 10 M $\Omega$ , and its unity-gain frequency is approximately 10 MHz.

### INPUT AND OUTPUT CAPACITORS

The input and output capacitors used in conjunction with the ML4900, especially in Pentium Pro VRM applications, must be able to meet several criteria:

1. The input capacitors must be able to handle a relatively high ripple current
2. The output capacitors must have a low Equivalent Series Resistance (ESR) and Equivalent Series Inductance (ESL)
3. The output capacitors must be able to hold up the output during the time that the current through the buck inductor is slewing to meet a transient load step.

The circuit's input bypass capacitance should be able to handle a ripple current equal to 0.5 x I<sub>LOAD</sub>. If the converter sees load peaks only occasionally, and for less than 30 seconds at a time during those intervals, then aluminum electrolytic or OS-Con input capacitors need only be sized to accommodate the average output load. Note that tantalum input capacitors have much less thermal mass than aluminum electrolytics, so this relaxation of ripple current requirements may not apply to them.

During a 30A/ $\mu$ s load transient, it is not possible for a buck converter to slew the output current fast enough to regulate the voltage in this application. During this interval, the output capacitance of the converter must act as passive energy storage. In delivering its energy to the load, the output capacitance must not introduce any considerable impedance, or its purpose will be defeated. A total voltage aberration during load transients of  $\pm$ 5% is allowed (see Intel AP-523). The voltage transient due to ESL and ESR is:

(1)

For example, assume that a 3.3V output has 3% of the output's  $\Delta$ V contributed by ESR (100mV) and 2% by the ESL (66mV). To meet this requirement, the output ESR

should not exceed:

$$ESR(MAX) = \frac{100mV}{13.7A} = 7.3m\Omega \quad (2)$$

With the effects of ESL limited to 2% of 3.3V, the maximum ESL is:

(3)

Achieving these low values of ESL and ESR is not trivial; doing so typically requires using several high-quality capacitors in parallel.

The output capacitance should have a value of > 2200 $\mu$ F to hold the output voltage relatively constant (< 50mV of sag) until the current in the buck inductor can catch up with the change in output current. To meet the ESR and ESL requirements, the actual output capacitance will usually be significantly greater than this theoretical minimum. These capacitors can be of all one type, or a combination of aluminum electrolytic, OS-Con, and tantalum devices.

### OVERCURRENT PROTECTION

Current sense resistor R1 is used to monitor the inductor current during the off period, i.e., while current is flowing through the synchronous rectifier (or Schottky diode, if no synchronous rectifier MOSFET is used). The internal current sense comparator has been designed to provide in excess of 14A of output current when used with a 5m $\Omega$  resistor. R1 must be a low inductance part such as Dale/Vishay's type WSL-2512-.005 $\pm$ 2.5%. This is a 5m $\Omega$  surface mount part rated at 1 Watt. Using a PCB trace as a current sense element is not recommended due to the high temperature coefficient of copper, and due to etching and plating tolerances which can occur from board to board.

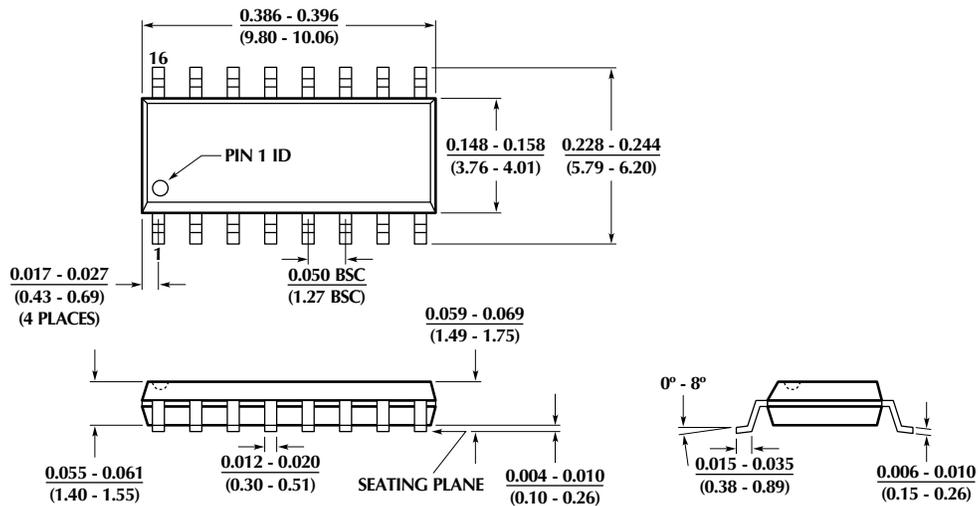
The R and C values connected to the PROTECT pin for setting the current limit delay and the off-time of the hiccup mode are 100k $\Omega$  and 1 $\mu$ F, respectively. These values will protect most MOSFETs from overheating during a short circuit condition. If it is necessary to change the ratio of ON and OFF times during overcurrent conditions, this can be done by selecting a different value for C13. Larger values of C13 will increase the delay between retry attempts (the length of the "hiccup").

The voltage across current sense resistor R1 must be Kelvin-sensed. This ensures that the ML4900 monitors only the voltage across this resistor and not the voltage drops or inductive transients in the PCB traces which carry current into and out of this resistor. The two pins of the ML4900 which must be Kelvin-connected to the sense resistor are I<sub>SENSE</sub> and GND. There is no connection inside the ML4900 between GND (pin 8) and PWR GND (pin 12). This is to facilitate the requisite Kelvin-sensing of the voltage across R1. Because of this, there must be a good electrical connection between the ML4900 PWR GND

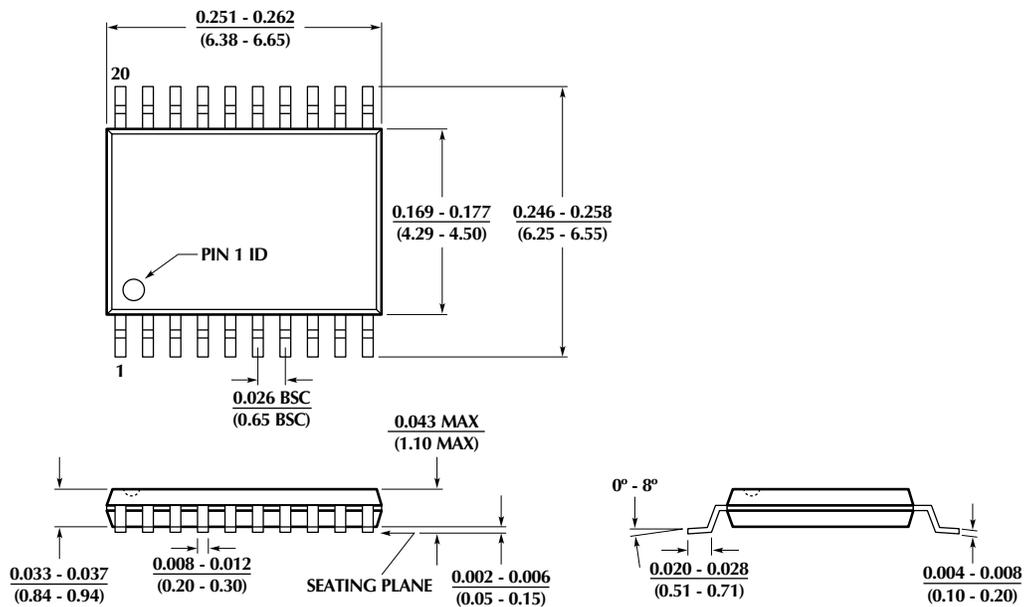


## PHYSICAL DIMENSIONS inches (millimeters)

**Package: S16N**  
**16-Pin Narrow SOIC**



**Package: T20**  
**20-Pin TSSOP**



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**ORDERING INFORMATION**

PART NUMBER	TEMPERATURE RANGE	PACKAGE
ML4900CS (End Of Life)	0°C to 70°C	16-Pin Narrow SOIC (S16N)
ML4900CT (Obsolete)	0°C to 70°C	20-Pin TSSOP (T20)

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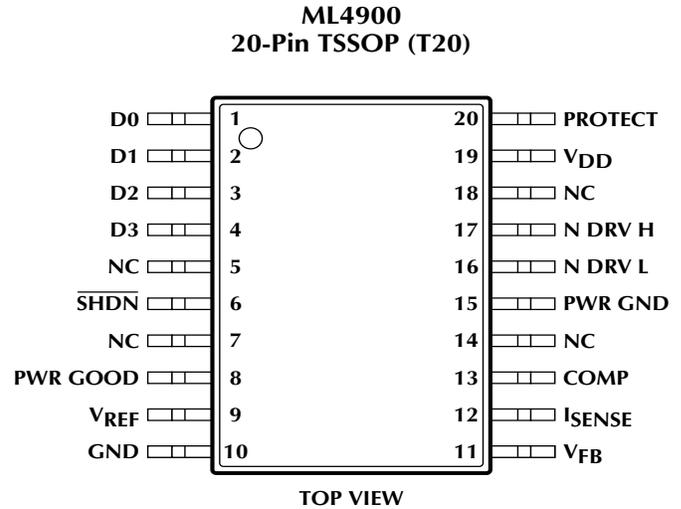
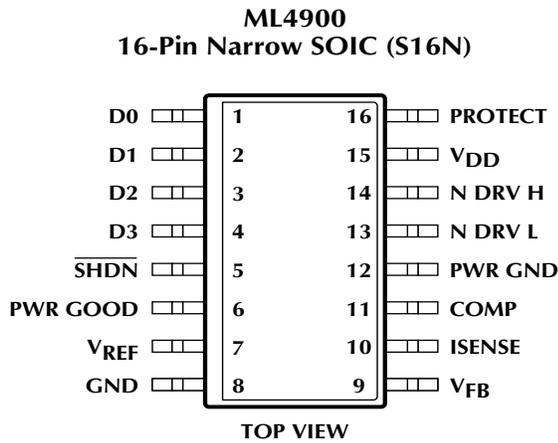
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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



# ML4900

## PIN CONFIGURATION



## PIN DESCRIPTION (Pin Number in Parentheses is for TSSOP Version)

PIN	NAME	FUNCTION	PIN	NAME	FUNCTION
1 (1)	D0	LSB input to the DAC which sets the output voltage	8 (10)	GND	Analog signal ground
2 (2)	D1	Input to the DAC which sets the output voltage	9 (11)	V <sub>FB</sub>	Output voltage feedback pin
3 (3)	D2	Input to the DAC which sets the output voltage	10 (12)	I <sub>SENSE</sub>	Current sense input
4 (4)	D3	MSB input to the DAC which sets the output voltage	11 (13)	COMP	Connection for the compensation and optional soft-start delay network
5 (6)	$\overline{\text{SHDN}}$	Grounding this pin shuts down the regulator	12 (15)	PWR GND	Power ground
6 (8)	PWR GOOD	This open collector output goes low whenever $\overline{\text{SHDN}}$ goes low or when the output is not within $\pm 10\%$ of its nominal value	13 (16)	N DRV L	Synchronous rectifier driver output
7 (9)	V <sub>REF</sub>	Bypass connection for the internal 3.5V reference	14 (17)	N DRV H	Buck switch driver output
			15 (19)	V <sub>DD</sub>	12V power supply input
			16 (20)	PROTECT	Connection for the integrating current limit network and the UVLO monitor for the 5V supply

## ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

V <sub>DD</sub> .....	13.5V
Peak Driver Output Current .....	±2A
V <sub>FB</sub> Voltage .....	GND - 0.3V to 5.5V
I <sub>SENSE</sub> Voltage .....	GND - 0.5V to 5.5V
All Other Analog Inputs .....	GND - 0.3V to V <sub>DD</sub> + 0.3V
$\overline{\text{SHDN}}$ Input Current .....	100µA
Junction Temperature .....	150°C
Storage Temperature Range .....	-65°C to 150°C

Lead Temperature (Soldering, 10 sec) .....	260°C
Thermal Resistance ( $\theta_{JA}$ )	
16-Pin Narrow SOIC .....	100°C/W
20-Pin TSSOP .....	143°C/W

## OPERATING CONDITIONS

Temperature Range .....	0°C to 70°C
V <sub>DD</sub> Range .....	11.4V to 12.6V
PROTECT (5V Supply) Range .....	4.75V to 5.25V

## ELECTRICAL CHARACTERISTICS

Unless otherwise specified, V<sub>DD</sub> = 12V, PROTECT =  $\overline{\text{SHDN}}$  = 5V, T<sub>A</sub> = Operating Temperature Range (Note 1)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>REFERENCE</b>						
V <sub>REF</sub>	Output Voltage		3.51	3.535	3.56	V
	Line Regulation	11V < V <sub>DD</sub> < 13V		0.5		mV/V
<b>UV LOCKOUT</b>						
	V <sub>DD</sub> Start-up Threshold		10.2	10.5	10.8	V
	V <sub>DD</sub> Hysteresis		300	450	600	mV
	PROTECT (5V) Start-up Threshold		4.25	4.4	4.5	V
	PROTECT (5V) Hysteresis		400	450	500	mV
<b>SHUTDOWN</b>						
	Input Low Voltage				0.8	V
	Input High Voltage		2.0			V
	Delay to Output			50		ns
<b>POWER GOOD COMPARATOR</b>						
	Output Voltage in Regulation	5kΩ pull-up to 5V	4.8			V
	Output Voltage out of Regulation	V <sub>FB</sub> < 90% V <sub>DAC</sub> or >110% V <sub>DAC</sub>			0.4	V
	Output Voltage in Shutdown	$\overline{\text{SHDN}}$ = 0V, 5kΩ pull-up to 5V			0.4	V
<b>BUCK REGULATOR</b>						
	Oscillator Frequency		160	200	230	kHz
	Duty Cycle Ratio	DAC (D3-D0) Code = 0100, V <sub>FB</sub> = 0V	85		95	%
		DAC (D3-D0) Code = 0100, V <sub>FB</sub> > 3.193V			0	%
	DAC (D3-D0) Input Low Voltage				0.8	V
	DAC (D3-D0) Input High Voltage		2.0			V

## ELECTRICAL CHARACTERISTICS (Continued)

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>BUCK REGULATOR (continued)</b>						
	V <sub>FB</sub> Threshold Voltage	DAC (D3-D0) Code = 0000	3.495	3.535	3.575	V
		DAC (D3-D0) Code = 0001	3.400	3.434	3.468	V
		DAC (D3-D0) Code = 0010	3.300	3.333	3.366	V
		DAC (D3-D0) Code = 0011	3.200	3.232	3.264	V
		DAC (D3-D0) Code = 0100	3.100	3.131	3.162	V
		DAC (D3-D0) Code = 0101	3.000	3.03	3.060	V
		DAC (D3-D0) Code = 0110	2.900	2.929	2.958	V
		DAC (D3-D0) Code = 0111	2.800	2.828	2.856	V
		DAC (D3-D0) Code = 1000	2.700	2.727	2.754	V
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		DAC (D3-D0) Code = 1010	2.500	2.525	2.550	V
		DAC (D3-D0) Code = 1011	2.400	2.424	2.448	V
		DAC (D3-D0) Code = 1100	2.299	2.323	2.347	V
		DAC (D3-D0) Code = 1101	2.198	2.222	2.246	V
		DAC (D3-D0) Code = 1110	2.097	2.121	2.145	V
	DAC (D3-D0) Code = 1111			0.8	V	
	I <sub>SENSE</sub> Threshold Voltage		-66	-73	-80	mV
	I <sub>SENSE</sub> Hysteresis			3		mV
	PROTECT Discharge Current	V(I <sub>SENSE</sub> ) = -100mV		35		mA
	PROTECT Leakage Current			±100		nA
	Transition Time, N DRV H and N DRV L	C <sub>L</sub> = 5000pF, 10-90%		40		ns
<b>SUPPLY</b>						
	V <sub>DD</sub> Current	$\overline{\text{SHDN}} = 0\text{V}$ DAC (D3-D0) Code = 0000		300	450	μA
		$\overline{\text{SHDN}} = 5\text{V}$ , V <sub>FB</sub> = 5V		1	2	mA
		$\overline{\text{SHDN}} = 5\text{V}$ , V <sub>FB</sub> = 0V, C <sub>L</sub> = 5000pF		30		mA

**Note 1:** Limits are guaranteed by 100% testing, sampling, or correlation with worst case test conditions.

## FUNCTIONAL DESCRIPTION

The ML4900 PWM controller permits the construction of a simple yet sophisticated power supply for Intel's Pentium Pro microprocessor which meets the guidelines of Intel's Application Note AP-523. This can be built either as a Voltage Regulator Module (VRM) or as dedicated motherboard circuitry. The ML4900 controls two N-channel MOSFETs in a synchronous buck regulator circuit, to convert a 5V input to the voltage required by the microprocessor. The output voltage can be any set to any one of 15 output voltages from 2.1V to 3.5V, in steps of 100mV, as selected by an onboard DAC. Other features which facilitate the design of DC-DC converters for any type of processor include a trimmed 1% reference, special transient-response optimization in the feedback paths, a shutdown input, input and output power good monitors, and overcurrent protection.

### 4-BIT DAC

The inputs of the internal 4-bit DAC come from open collector signals provided by the Pentium Pro. These signals specify what supply voltage the microprocessor requires. The output voltage of the buck converter is compared directly with the DAC voltage to maintain regulation. D3 is the MSB input and D0 is the LSB input of the DAC. The output voltage set by the DAC is 1% above the Pentium Pro's nominal operating voltage to counteract the effects of connector and PC trace resistance, and of the instantaneous output voltage droop which occurs when a transient load is applied. The output of the DAC therefore ranges from 2.121V to 3.535V in 100mV steps. For code 1111, the N DRV H output is disabled, and the output voltage is zero.

### VOLTAGE FEEDBACK LOOP

The ML4900 contains two control loops to improve the load transient response. The output voltage is directly monitored via the  $V_{FB}$  pin and compared to the desired output voltage set by the internal 4-bit DAC. When the output voltage is within  $\pm 3\%$  of the DAC voltage, the proportional control loop (closed by the voltage error amplifier) keeps the output voltage at the correct value. If the output falls below the DAC voltage by more than 3%, one side of the transient loop is activated, forcing the output of the ML4900 to maximum duty cycle until the output comes back within the  $\pm 3\%$  limit. If the output voltage rises above the DAC voltage by more than 3%, the other side of the transient loop is activated, and the upper MOSFET drive is disabled until the output comes back within the  $\pm 3\%$  limit. During start-up, the transient loop is disabled until the output voltage is within -3% of the DAC voltage.

### POWER GOOD (PWR GOOD)

An open drain signal is provided by the ML4900 which tells the microprocessor when the entire power system is

functioning within the expected limits. PWR GOOD will be false (low) if either the 5V or 12V supply is not in regulation, when the  $\overline{\text{SHDN}}$  pin is pulled low, or when the output is not within  $\pm 10\%$  of the nominal output voltage selected by the internal DAC.

When PWR GOOD is false, the PWR GOOD voltage window is held to  $\pm 3\%$ ; when PWR GOOD is true (high), the window is expanded to  $\pm 10\%$ . Using different windows for coming into and going out of regulation makes sure that PWR GOOD does not oscillate during the start-up of the microprocessor.

### INTERNAL REFERENCE

The ML4900 contains a 3.535V, temperature compensated, precision band-gap reference. The  $V_{REF}$  pin is connected to the output of this reference, and should be bypassed with a 100nF to 220nF ceramic capacitor for proper operation.

### OVERCURRENT PROTECTION

When the output of the buck converter sees an overcurrent condition ( $I_{OUT}$  exceeds the current limit set point  $I_{SET}$ ), the ML4900 will operate in a "hiccup" mode until the overcurrent condition has been removed.

During an overcurrent condition, a current sink within the ML4900 draws a small current (35 $\mu$ A) out of the PROTECT pin for the time during which  $I_{OUT} > I_{SET}$ . If this current sink is activated over a number of cycles, the voltage on the PROTECT pin will drop below 4V, signalling a sustained overcurrent or short circuit at the load. This will cause the N DRV H output to turn off. The converter will remain in an off state until the capacitor attached to the PROTECT pin has charged back to 4.4V, at which time the converter is re-enabled and tries to resume normal operation. If the fault causing the overcurrent condition has not been cleared, the overcurrent protection cycle will repeat.

### UNDERVOLTAGE LOCKOUT

The ML4900 has undervoltage lockout protection circuits for both the 12V ( $V_{DD}$ ) and 5V (PROTECT) supplies. The hysteresis voltage is typically 400mV for each supply. During an input undervoltage condition, the internal reference and voltage monitor circuits remain in operation, but N DRV H and N DRV L are disabled and the PWR GOOD output will be false (low).

### COMPENSATION/SOFT-START

This pin connects to the output of the transconductance amplifier which forms the gain block for the ML4900's proportional control loop. An RC network from this pin to GND is used to compensate the amplifier.

## DESIGN CONSIDERATIONS

This section is a quick-check guide for getting ML4900 circuits up and running, with a special emphasis on Pentium Pro applications. All component designators refer to the circuit shown in Figure 1.

### COMPENSATION

The R and C values connected to the COMP pin for loop compensation are 330k $\Omega$  and 33pF, respectively. These values yield stable operation and rapid transient response for a most values of L and C<sub>OUT</sub> (1 $\mu$ H to 5 $\mu$ H, 1200 $\mu$ F to 10,000 $\mu$ F), and will generally not need to be altered. If changes do need to be made, note that the drive capability of the transconductance error amplifier is typically 10 $\mu$ A, its Z<sub>OUT</sub> is 10 M $\Omega$ , and its unity-gain frequency is approximately 10 MHz.

### INPUT AND OUTPUT CAPACITORS

The input and output capacitors used in conjunction with the ML4900, especially in Pentium Pro VRM applications, must be able to meet several criteria:

1. The input capacitors must be able to handle a relatively high ripple current
2. The output capacitors must have a low Equivalent Series Resistance (ESR) and Equivalent Series Inductance (ESL)
3. The output capacitors must be able to hold up the output during the time that the current through the buck inductor is slewing to meet a transient load step.

The circuit's input bypass capacitance should be able to handle a ripple current equal to 0.5 x I<sub>LOAD</sub>. If the converter sees load peaks only occasionally, and for less than 30 seconds at a time during those intervals, then aluminum electrolytic or OS-Con input capacitors need only be sized to accommodate the average output load. Note that tantalum input capacitors have much less thermal mass than aluminum electrolytics, so this relaxation of ripple current requirements may not apply to them.

During a 30A/ $\mu$ s load transient, it is not possible for a buck converter to slew the output current fast enough to regulate the voltage in this application. During this interval, the output capacitance of the converter must act as passive energy storage. In delivering its energy to the load, the output capacitance must not introduce any considerable impedance, or its purpose will be defeated. A total voltage aberration during load transients of  $\pm$ 5% is allowed (see Intel AP-523). The voltage transient due to ESL and ESR is:

(1)

For example, assume that a 3.3V output has 3% of the output's  $\Delta$ V contributed by ESR (100mV) and 2% by the ESL (66mV). To meet this requirement, the output ESR

should not exceed:

$$ESR(\text{MAX}) = \frac{100\text{mV}}{13.7\text{A}} = 7.3\text{m}\Omega \quad (2)$$

With the effects of ESL limited to 2% of 3.3V, the maximum ESL is:

(3)

Achieving these low a values of ESL and ESR is not trivial; doing so typically requires using several high-quality capacitors in parallel.

The output capacitance should have a value of > 2200 $\mu$ F to hold the output voltage relatively constant (< 50mV of sag) until the current in the buck inductor can catch up with the change in output current. To meet the ESR and ESL requirements, the actual output capacitance will usually be significantly greater than this theoretical minimum. These capacitors can be of all one type, or a combination of aluminum electrolytic, OS-Con, and tantalum devices.

### OVERCURRENT PROTECTION

Current sense resistor R1 is used to monitor the inductor current during the off period, i.e., while current is flowing through the synchronous rectifier (or Schottky diode, if no synchronous rectifier MOSFET is used). The internal current sense comparator has been designed to provide in excess of 14A of output current when used with a 5m $\Omega$  resistor. R1 must be a low inductance part such as Dale/Vishay's type WSL-2512-.005 $\pm$ 2.5%. This is a 5m $\Omega$  surface mount part rated at 1 Watt. Using a PCB trace as a current sense element is not recommended due to the high temperature coefficient of copper, and due to etching and plating tolerances which can occur from board to board.

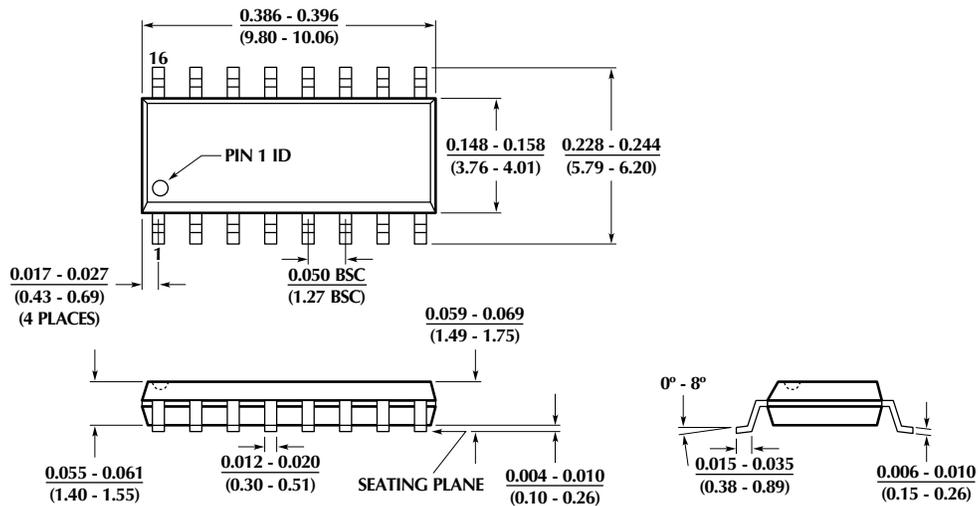
The R and C values connected to the PROTECT pin for setting the current limit delay and the off-time of the hiccup mode are 100k $\Omega$  and 1 $\mu$ F, respectively. These values will protect most MOSFETs from overheating during a short circuit condition. If it is necessary to change the ratio of ON and OFF times during overcurrent conditions, this can be done by selecting a different value for C13. Larger values of C13 will increase the delay between retry attempts (the length of the "hiccup").

The voltage across current sense resistor R1 must be Kelvin-sensed. This ensures that the ML4900 monitors only the voltage across this resistor and not the voltage drops or inductive transients in the PCB traces which carry current into and out of this resistor. The two pins of the ML4900 which must be Kelvin-connected to the sense resistor are I<sub>SENSE</sub> and GND. There is no connection inside the ML4900 between GND (pin 8) and PWR GND (pin 12). This is to facilitate the requisite Kelvin-sensing of the voltage across R1. Because of this, there must be a good electrical connection between the ML4900 PWR GND

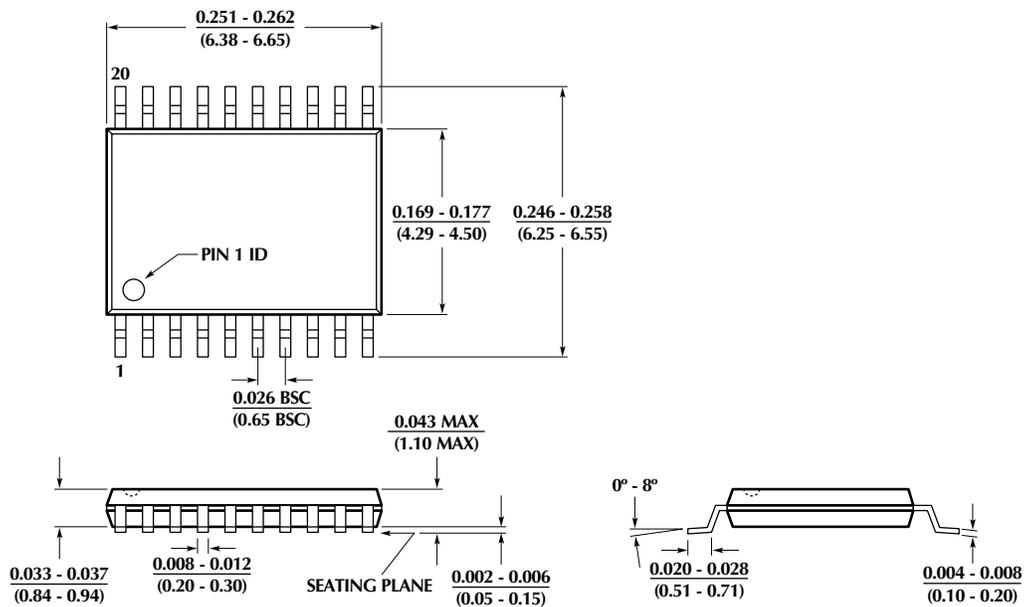


## PHYSICAL DIMENSIONS inches (millimeters)

**Package: S16N**  
**16-Pin Narrow SOIC**



**Package: T20**  
**20-Pin TSSOP**



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**ORDERING INFORMATION**

PART NUMBER	TEMPERATURE RANGE	PACKAGE
ML4900CS (End Of Life)	0°C to 70°C	16-Pin Narrow SOIC (S16N)
ML4900CT (Obsolete)	0°C to 70°C	20-Pin TSSOP (T20)

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